



TMRC 2022

The 33rd Magnetic Recording Conference

August 29-31, <https://tmrc22.sites.stanford.edu/>

CALL FOR NOMINATIONS

The 33rd Magnetic Recording Conference will be held at Western Digital Milpitas campus on August 29-31, 2022. The focus of TMRC 2022 is **Solid State Magnetic Memory and Recording Technologies for >3 Tbits/in²**

Approximately 36 invited papers of the highest quality will be presented orally at the conference and will later be published in the IEEE Transactions on Magnetics. Poster sessions will also be held following the oral sessions and will feature posters from the invited speakers and accepted contributed posters. Presenters of invited & contributed papers are encouraged for publication.

Topics of interest include:

- Solid State Memory – Devices and Applications
 - Spin Transfer Torque-Magnetic Random Access Memory (MTJ cell, MRAM chip manufacturing and roadmap)
 - MRAM– New Physics & Materials (MRAM architecture, VC-MRAM, SOT-MRAM, TI & 2D materials)
 - New Architectures and Applications for In-Memory and Near Memory Compute, Advanced Memory Bus Architectures, AI, ML and Neuromorphic Compute, 2.5 and 3D applications, Harsh environments
- Advanced Generation Recording Technologies
 - Heat Assisted Magnetic Recording (HAMR System, Head/Media and HDI)
 - Microwave-Assisted Magnetic Recording (MAMR)
 - Alternative Magnetic Recording Technologies (EAMR, SMR, TDMR, HIMR, Heated-dot, Tape, All Optical Switching)
 - Advanced Magnetic Recording for > 3 Tbits/in² including Readers, Writers, Servo, Tribology, HDI, Signal Processing
- Recording and Memory Fundamentals (Metrology, Tooling, Device Processing, Materials, Recording Physics)

By completing this [online form](#), nominations for invited speakers are submitted to the Program Chairs. The deadline to submit nominations is April 11, 2022.

TMRC 2022 is sponsored by the IEEE Magnetics Society and co-sponsored by the Center for Magnetic Nanotechnology (Stanford), DSSC (CMU), CMRR (UCSD), MINT Center (Univ. of Minnesota), and the Computer Mechanics Laboratory (UC Berkeley).



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